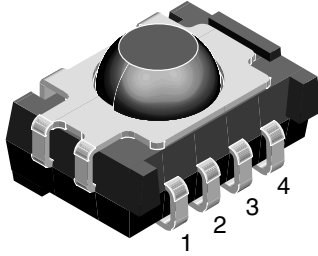


IR Receiver Modules for Remote Control Systems



16797

MECHANICAL DATA

Pinning:

1 = GND, 2 = GND, 3 = V_S , 4 = OUT

FEATURES

- Very low supply current
- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Supply voltage range: 2.5 V to 5.5 V
- Improved immunity against modulated light sources
- Insensitive to supply voltage ripple and noise
- Taping available for topview and sideview assembly
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



DESCRIPTION

The TSOP352..., TSOP354.. series are miniaturized SMD IR receiver modules for infrared remote control systems. PIN diode and preamplifier are assembled on lead frame, the epoxy package is designed as IR filter.

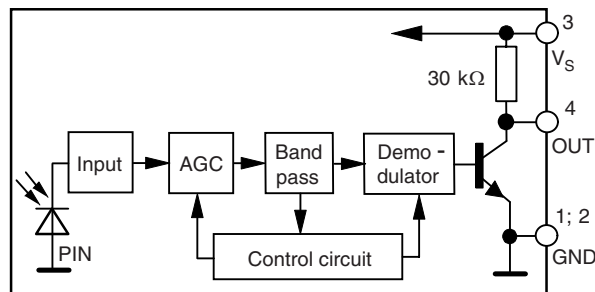
The demodulated output signal can directly be decoded by a microprocessor. The TSOP352.. is compatible with all common IR remote control data formats. The TSOP354.. is optimized to suppress almost all spurious pulses from energy saving lamps but will also suppress some data signals.

This component has not been qualified according to automotive specifications.

PARTS TABLE

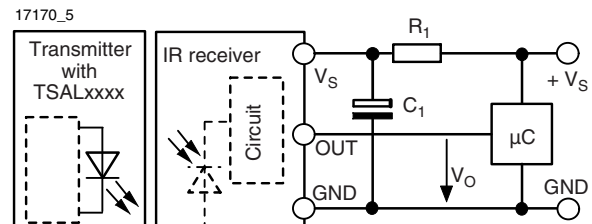
CARRIER FREQUENCY	STANDARD APPLICATIONS (AGC2/AGC8)	VERY NOISY ENVIRONMENTS (AGC4)
30 kHz	TSOP35230	TSOP35430
33 kHz	TSOP35233	TSOP35433
36 kHz	TSOP35236	TSOP35436
38 kHz	TSOP35238	TSOP35438
40 kHz	TSOP35240	TSOP35440
56 kHz	TSOP35256	TSOP35456

BLOCK DIAGRAM



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APPLICATION CIRCUIT



R_1 and C_1 are recommended for protection against EOS. Components should be in the range of $33 \Omega < R_1 < 1 \text{ k}\Omega$, $C_1 > 0.1 \mu\text{F}$.

ABSOLUTE MAXIMUM RATINGS (1)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Supply voltage (pin 3)		V_S	- 0.3 to + 6.0	V
Supply current (pin 3)		I_S	3	mA
Output voltage (pin 4)		V_O	- 0.3 to ($V_S + 0.3$)	V
Output current (pin 4)		I_O	5	mA
Junction temperature		T_j	100	°C
Storage temperature range		T_{stg}	- 40 to + 100	°C
Operating temperature range		T_{amb}	- 30 to + 85	°C
Power consumption	$T_{amb} \leq 85$ °C	P_{tot}	10	mW

Note

(1) Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability.

ELECTRICAL AND OPTICAL CHARACTERISTICS (1)

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply current (pin 3)	$E_v = 0$, $V_S = 3.3$ V	I_{SD}	0.27	0.35	0.45	mA
	$E_v = 40$ klx, sunlight	I_{SH}		0.45		mA
Supply voltage		V_S	2.5		5.5	V
Transmission distance	$E_v = 0$, test signal see fig. 1, IR diode TSAL6200, $I_F = 250$ mA	d		45		m
Output voltage low (pin 4)	$I_{OSL} = 0.5$ mA, $E_e = 0.7$ mW/m ² , test signal see fig. 1	V_{OSL}			100	mV
Minimum irradiance	Pulse width tolerance: $t_{pi} - 5/f_0 < t_{po} < t_{pi} + 6/f_0$, test signal see fig. 1	E_e min.		0.15	0.35	mW/m ²
Maximum irradiance	$t_{pi} - 5/f_0 < t_{po} < t_{pi} + 6/f_0$, test signal see fig. 1	E_e max.	30			W/m ²
Directivity	Angle of half transmission distance	$\phi_{1/2}$		± 50		deg

Note

(1) $T_{amb} = 25$ °C, unless otherwise specified

TYPICAL CHARACTERISTICS

$T_{amb} = 25$ °C, unless otherwise specified

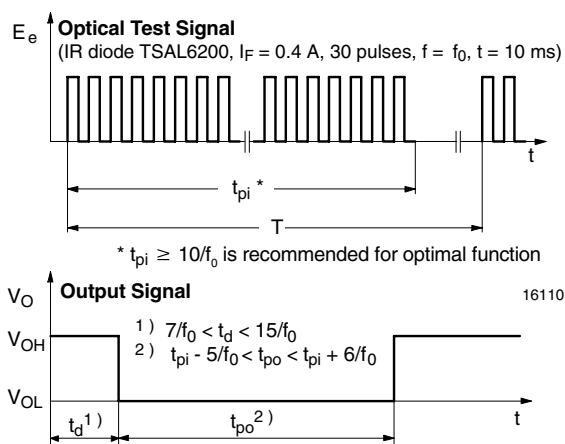


Fig. 1 - Output Active Low

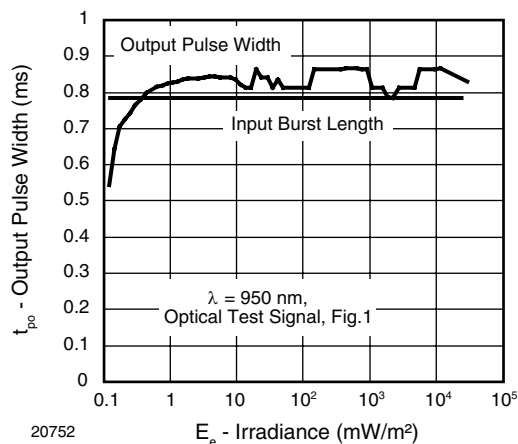


Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

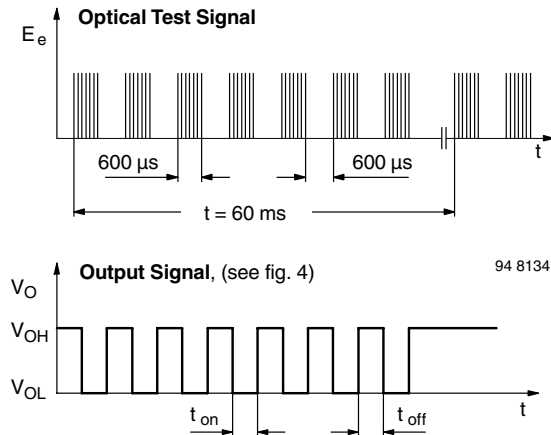


Fig. 3 - Output Function

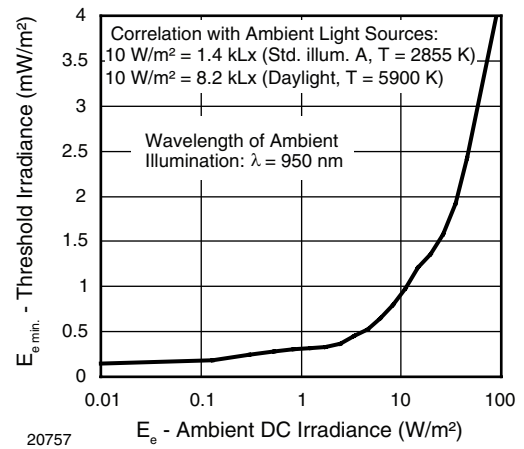


Fig. 6 - Sensitivity in Bright Ambient

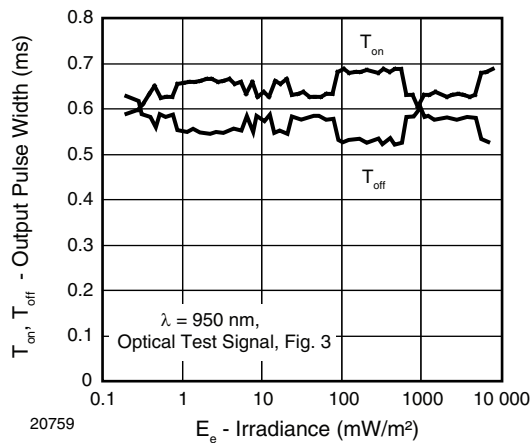


Fig. 4 - Output Pulse Diagram

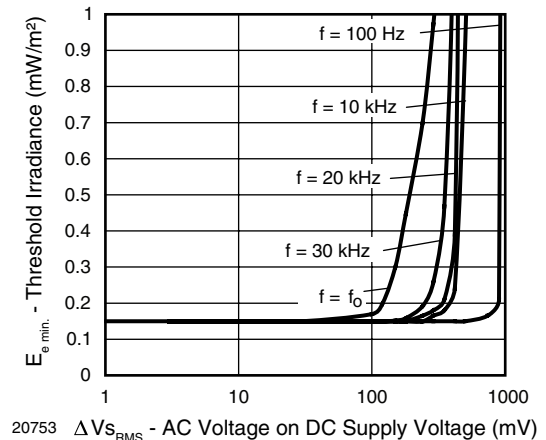


Fig. 7 - Sensitivity vs. Supply Voltage Disturbances

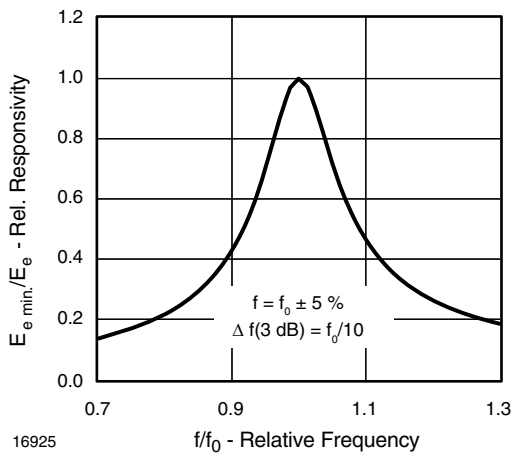


Fig. 5 - Frequency Dependence of Responsivity

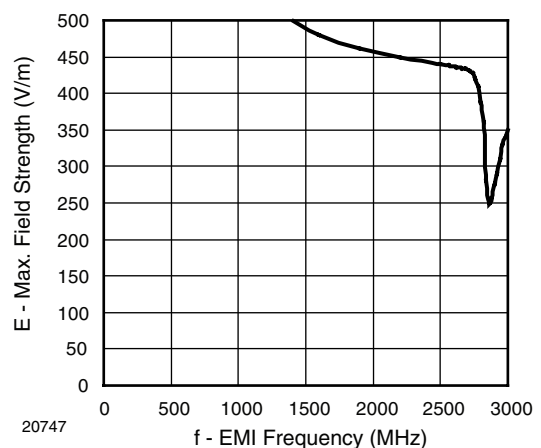


Fig. 8 - Sensitivity vs. Electric Field Disturbances

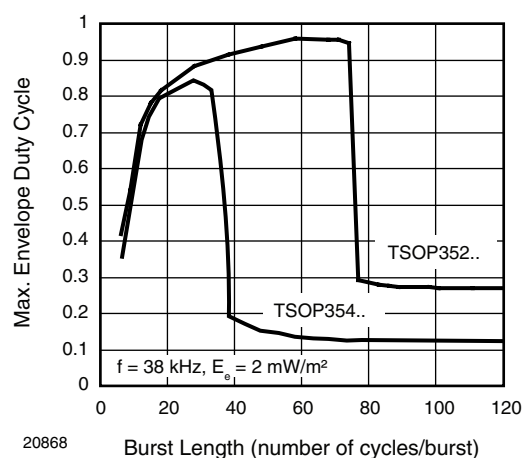


Fig. 9 - Maximum Envelope Duty Cycle vs. Burst Length

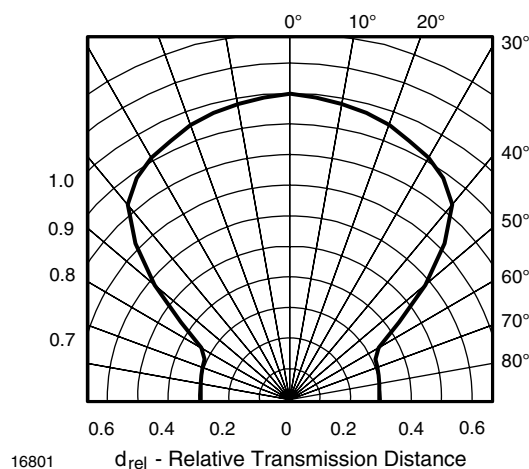


Fig. 12 - Horizontal Directivity

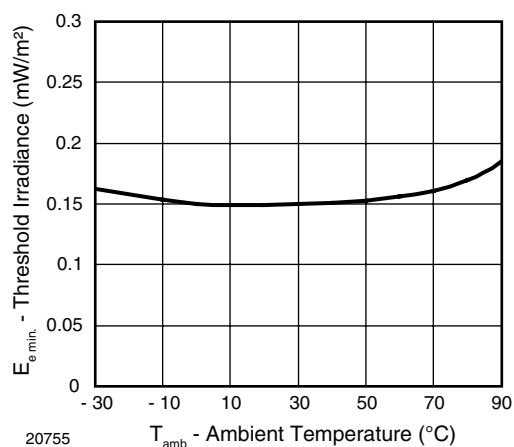


Fig. 10 - Sensitivity vs. Ambient Temperature

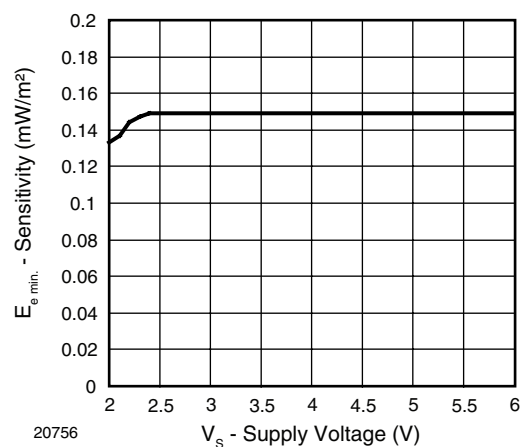


Fig. 13 - Sensitivity vs. Supply Voltage

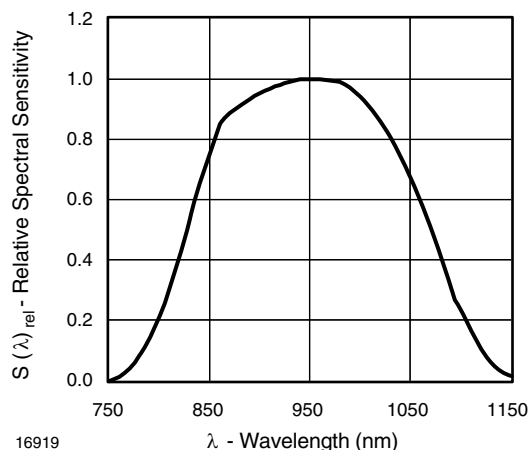


Fig. 11 - Relative Spectral Sensitivity vs. Wavelength



SUITABLE DATA FORMAT

The TSOP352.., TSOP354.. series is designed to suppress spurious output pulses due to noise or disturbance signals. Data and disturbance signals can be distinguished by the devices according to carrier frequency, burst length and envelope duty cycle. The data signal should be close to the band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.

When a data signal is applied to the TSOP352.., TSOP354.. in the presence of a disturbance signal, the sensitivity of the receiver is reduced to insure that no spurious pulses are present at the output. Some examples of disturbance signals which are suppressed are

- DC light (e.g. from tungsten bulb or sunlight)
- Continuous signals at any frequency
- Strongly or weakly modulated noise from fluorescent lamps with electronic ballasts (see figure 14 or figure 15)

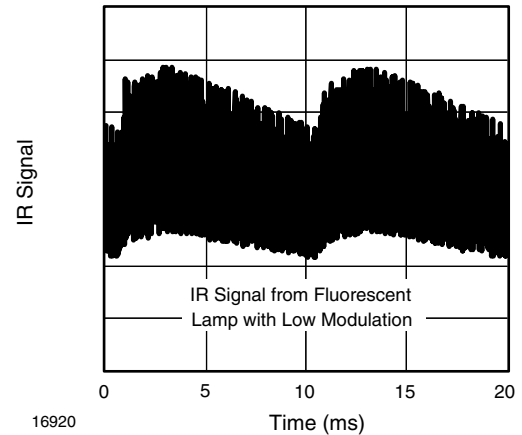


Fig. 14 - IR Signal from Fluorescent Lamp with Low Modulation

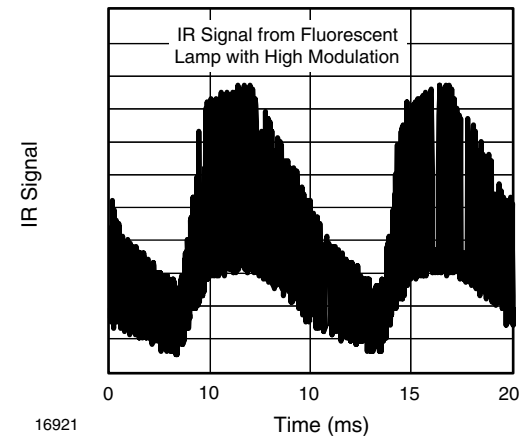


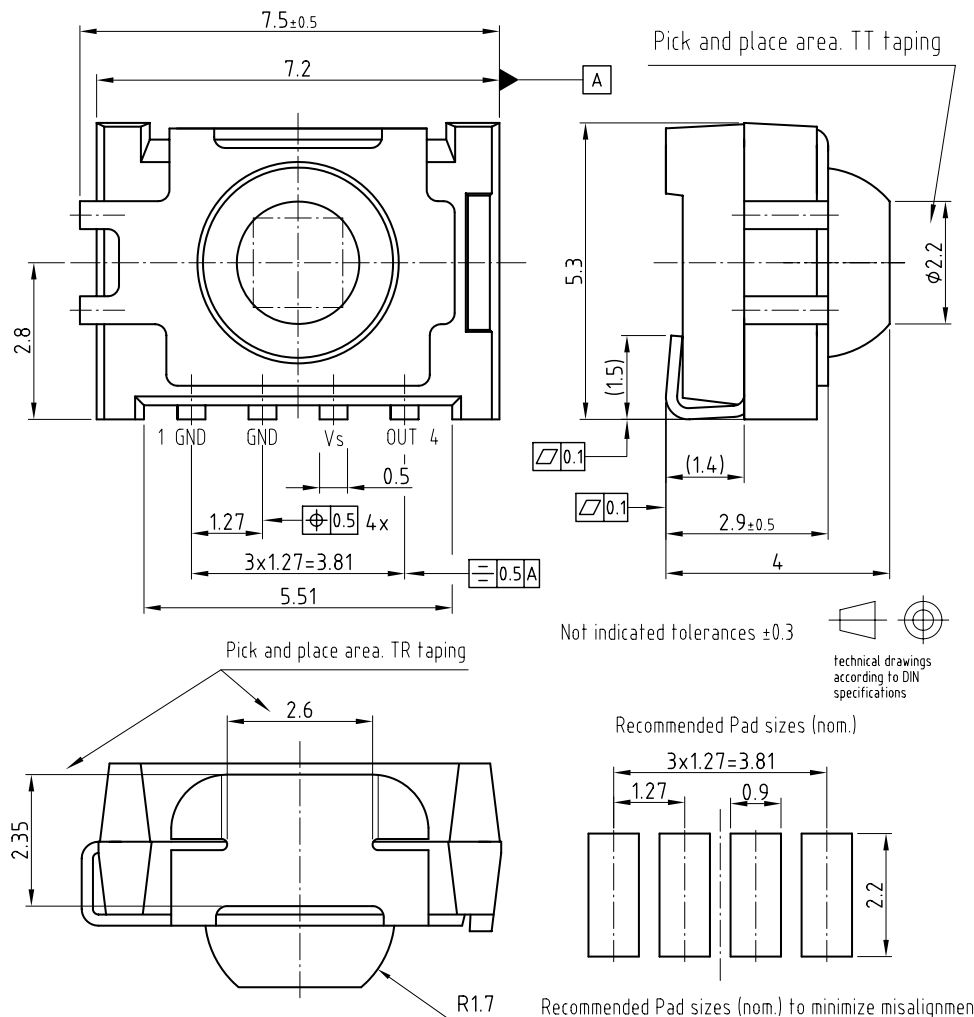
Fig. 15 - IR Signal from Fluorescent Lamp with High Modulation

	TSOP352..	TSOP354..
Minimum burst length	10 cycles/burst	10 cycles/burst
After each burst of length a minimum gap time is required of	10 to 70 cycles ≥ 10 cycles	10 to 35 cycles ≥ 10 cycles
For bursts greater than a minimum gap time in the data stream is needed of	70 cycles > 4 x burst length	35 cycles > 10 x burst length
Maximum number of continuous short bursts/second	1800	1500
Compatible to NEC code	yes	yes
Compatible to RC5/RC6 code	yes	yes
Compatible to Sony code	yes	no
Compatible to Thomson 56 kHz code	yes	yes
Compatible to Mitsubishi code (38 kHz, preburst 8 ms, 16 bit)	yes	no
Compatible to Sharp code	yes	yes
Suppression of interference from fluorescent lamps	Most common disturbance signals are suppressed	Even extreme disturbance signals are suppressed

Note

For data formats with short bursts please see the datasheet for TSOP351.., TSOP353..

PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.544-5341.02-4

Issue: 8; 07.03.08

16629

ASSEMBLY INSTRUCTIONS

Reflow Soldering

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified

that the temperature of the device is accurately being measured

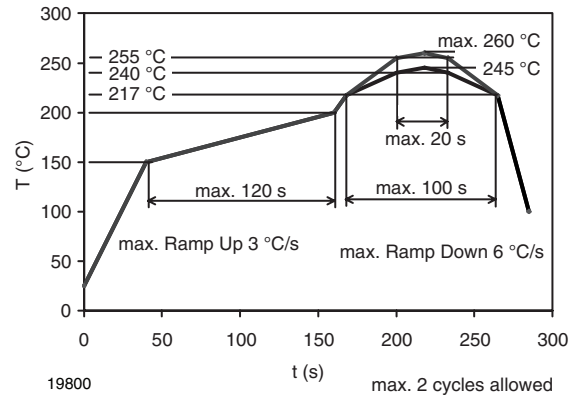
- Handling after reflow should be done only after the work surface has been cooled off

Manual Soldering

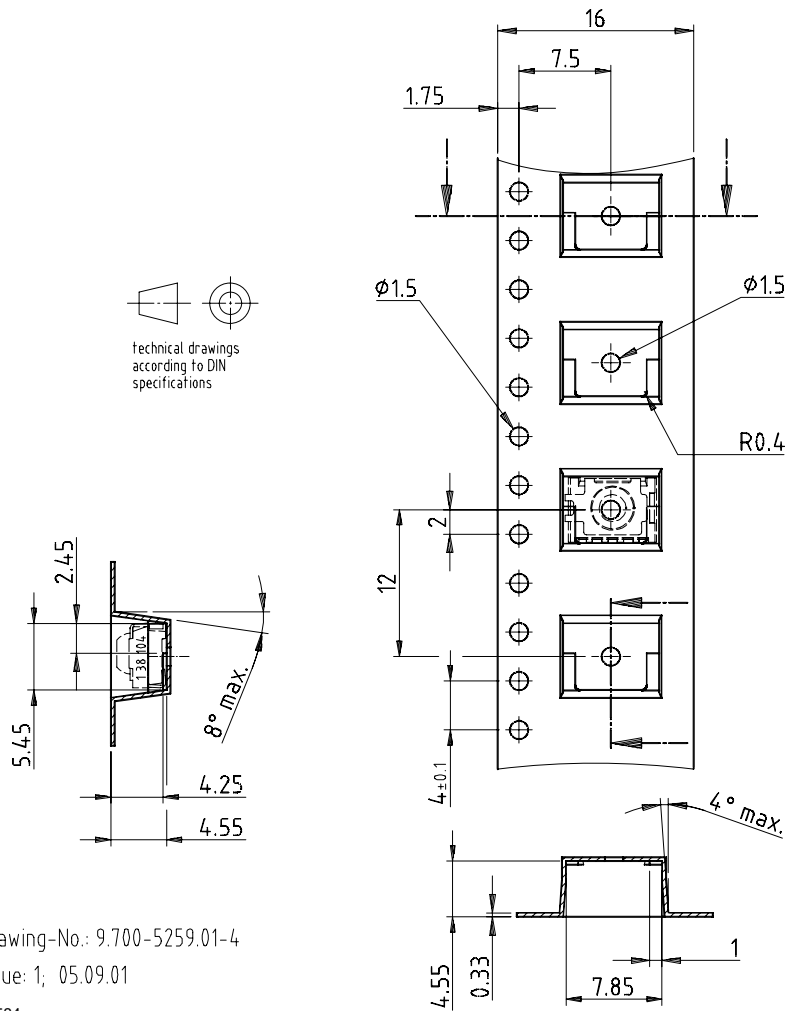
- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off



VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE



TAPING VERSION TSOP..TT Dimensions in millimeters

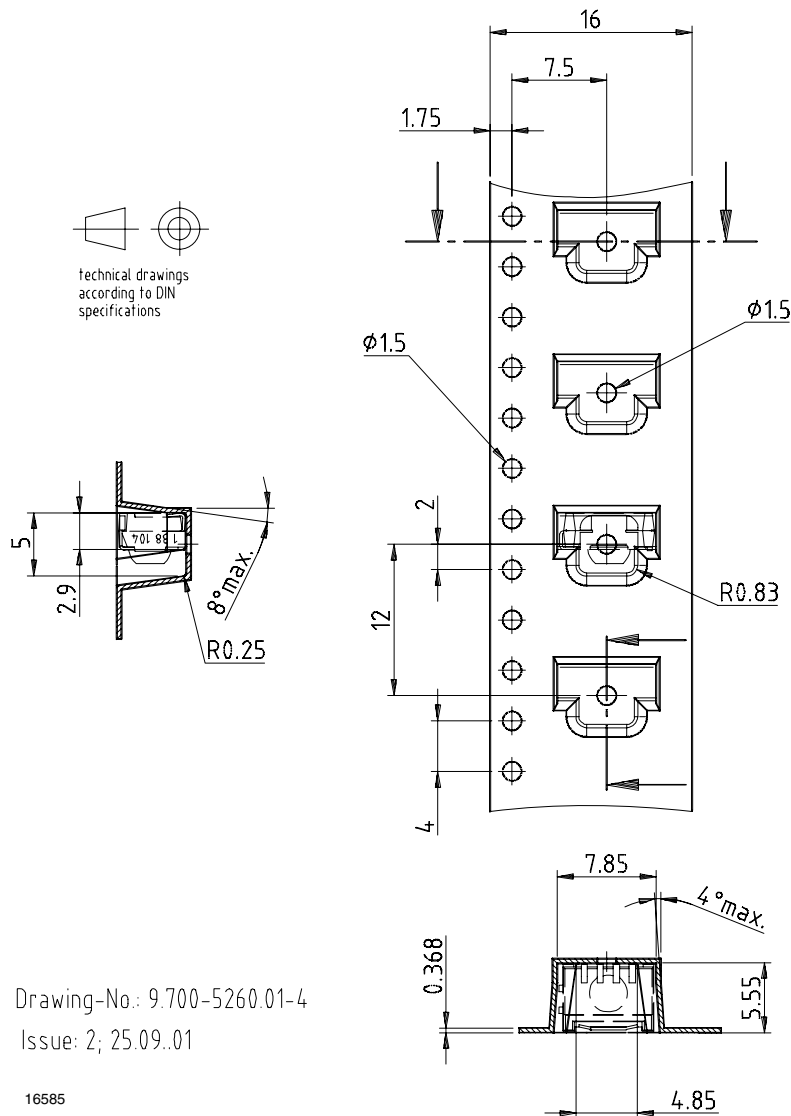


Drawing-No.: 9.700-5259.01-4

Issue: 1; 05.09.01

16584

TAPING VERSION TSOP..TR Dimensions in millimeters

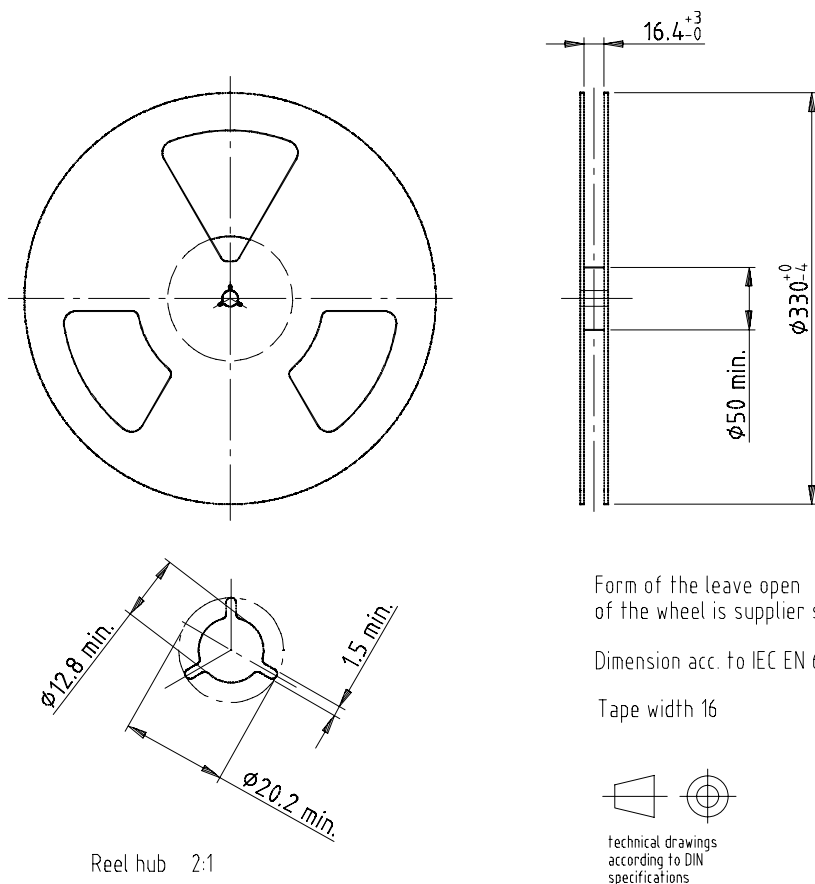


Drawing-No.: 9.700-5260.01-4

Issue: 2; 25.09.01

16585

REEL DIMENSIONS in millimeters



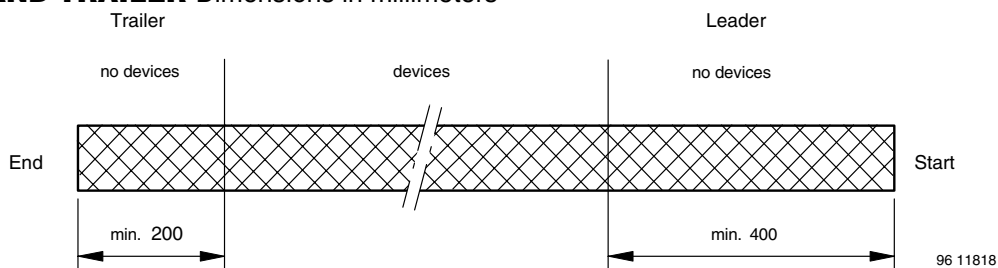
Drawing refers to following types: Reel for blister carrier tape Version B

Drawing-No.: 9.800-5052.V2-4

Issue: 1; 07.05.02

16734

LEADER AND TRAILER Dimensions in millimeters



COVER TAPE PEEL STRENGTH

According to DIN EN 60286-3

0.1 to 1.3 N

300 ± 10 mm/min.

165° to 180° peel angle

LABEL

Standard bar code labels for finished goods

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.

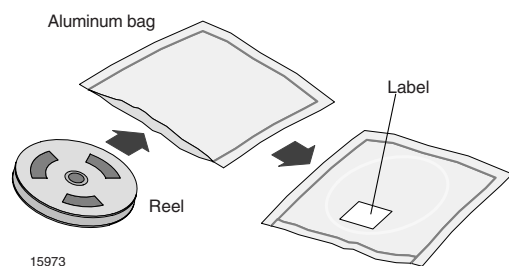
VISHAY SEMICONDUCTOR GMBH STANDARD BAR CODE PRODUCT LABEL (Finished Goods)		
PLAIN WRITTING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
LONG BAR CODE TOP	TYPE	LENGTH
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
SHORT BAR CODE BOTTOM	TYPE	LENGTH
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17

DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.

FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.





RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity $\leq 60\%$ RH max.

After more than 72 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at 40 °C + 5 °C/ - 0 °C and $< 5\%$ RH (dry air/nitrogen) or

96 h at 60 °C + 5 °C and $< 5\%$ RH for all device containers or
24 h at 125 °C + 5 °C not suitable for reel or tubes.

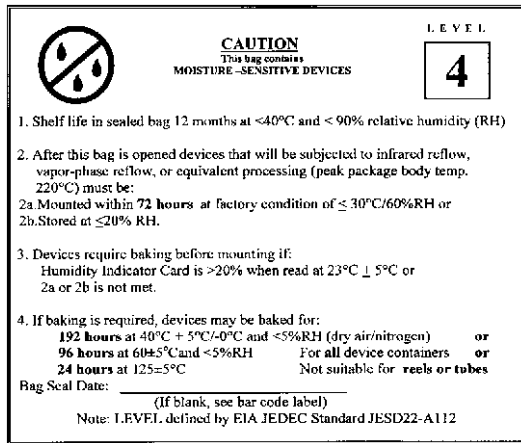
An EIA JEDEC standard JESD22-A112 level 4 label is included on all dry bags.

VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Telefunken specific data.



16962



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Example of JESD22-A112 level 4 label

ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electro-static sensitive devices warning labels are on the packaging.



OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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